

Part Number: XZUR74W

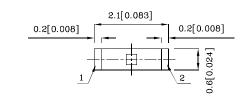
2.1x0.6mm RIGHT ANGLE SURFACE LED LAMP

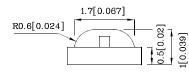
Features

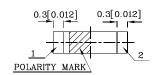
- \bullet Ideal for indication light on hand held products
- \bullet Long life and robust package
- Variety of lens types and color choices available
- Package: 2000pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant











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1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.

3. Specifications are subject to change without notice.

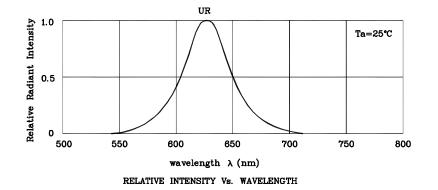
Absolute Maximum Ratings T _A =25°C)		UR (GaAsP/ GaP)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	160	mA	
Power Dissipation	\mathbf{P}_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	$-40 \sim +85$		

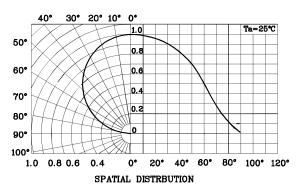
Operating Characteristics (T _A =25°C)		UR (GaAsP/GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V	
Reverse Current (Max.) (V _R =5V)	I_R	10	uA	
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λP	627	nm	
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λD	625	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	45	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	$_{\rm pF}$	

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZUR74W	Red	GaAsP/GaP	Water Clear	8	14	627	120°

XDSA1421 V8 Layout: Maggie L.







♦ UR

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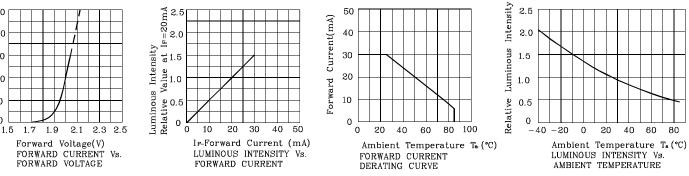
30

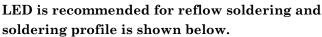
20

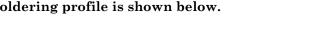
10

0

Forward Current(mA)







Reflow Soldering Profile for SMD Products (Pb-Free Components)

300 (°C) 10 s max iner? 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 60~120: 100 50 0 150 0 50 100 200 250 300 (sec) Time Notes: 1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C

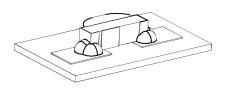
Do not put stress to the epoxy resin during З.

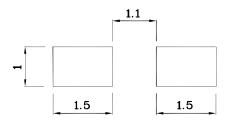
high temperatures conditions



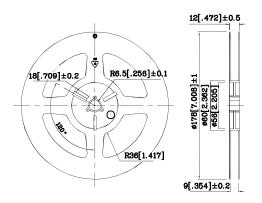
The device has a single mounting surface. The device must be mounted according to the specifications.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

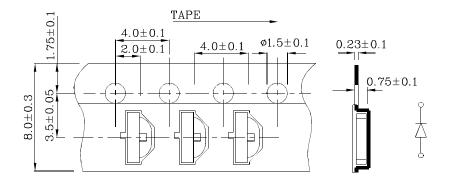




Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

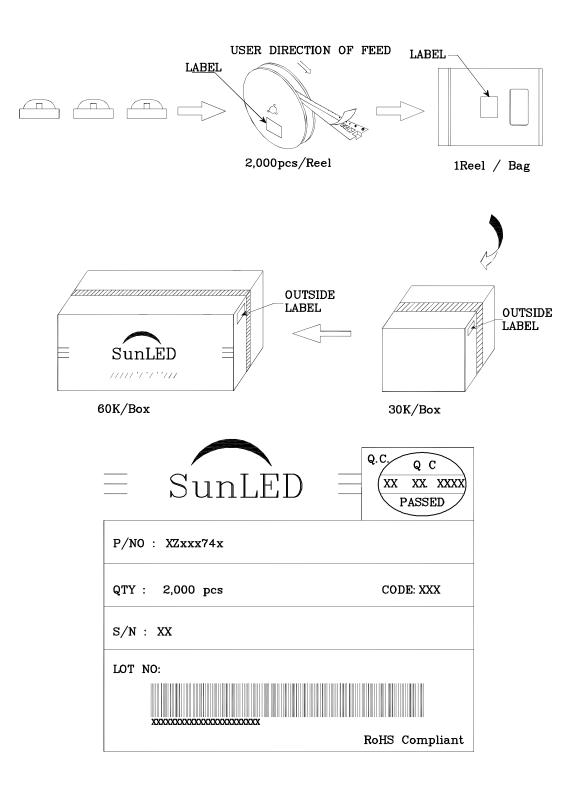
3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.

Mar 28,2011



PACKING & LABEL SPECIFICATIONS



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